

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	9365148
<b>Application Number:</b>	10786807
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	3341
<b>Title of Invention:</b>	Method for improving semiconductor wafer test accuracy
<b>First Named Inventor/Applicant Name:</b>	Hui-Mei Chen
<b>Customer Number:</b>	89518
<b>Filer:</b>	Dennis Alan Duchene/NICOLE SAN NICOLAS
<b>Filer Authorized By:</b>	Dennis Alan Duchene
<b>Attorney Docket Number:</b>	085027-0106
<b>Receipt Date:</b>	02-FEB-2011
<b>Filing Date:</b>	25-FEB-2004
<b>Time Stamp:</b>	20:47:18
<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$ 670
RAM confirmation Number	4693
Deposit Account	502624
Authorized User	

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## File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	TRANSMITTAL-085027-0106.pdf	20716	no	1
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Information:					
2		AMENDMENT-085027-0106.pdf	71425	yes	9
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	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Amendment/Req. Reconsideration-After Non-Final Reject		1	1	
	Claims		2	4	
	Applicant Arguments/Remarks Made in an Amendment		5	9	
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Information:					
3	Transmittal Letter	IDS-085027-0106.pdf	22283	no	2
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4	Information Disclosure Statement (IDS) Filed (SB/08)	IDS1449-085027-0106.pdf	86706	no	3
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5	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221	no	4
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6	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109	no	9
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7	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666	no	7
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33	Fee Worksheet (PTO-875)	fee-info.pdf	31844	no	2
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<b>Total Files Size (in bytes):</b>	41008949
<p><b>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</b></p> <p><b><u>New Applications Under 35 U.S.C. 111</u></b> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><b><u>National Stage of an International Application under 35 U.S.C. 371</u></b> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><b><u>New International Application Filed with the USPTO as a Receiving Office</u></b> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>	